

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Currently Amended) An electroless copper plating solution method, wherein, along with a first reducing agent, using an electroless copper plating solution comprising hypophosphorous acid or a hypophosphite is used as a second reducing agent, and along with a first reducing agent and further comprising a stabilizer to inhibit copper deposition is further used at the same time, a mirror surface whose average surface roughness is less than 10 nm is electroless plated to produce a thin film with a thickness of 500 nm or less.

2. (Canceled)

3. (Canceled)

4. (New) An electroless copper plating method according to Claim 1, wherein a pretreatment agent is prepared by reacting or mixing in advance a noble metal compound and a silane coupling agent having a functional group with metal capturing capability, and said mirror surface is treated with the pretreatment agent.

5. (New) An electroless copper plating method according to Claim 1, wherein the first reducing agent is glyoxylic acid, the second reducing agent is hypophosphorous acid and the stabilizer to inhibit copper deposition is 2,2'-bipyridyl.